Thermal Jumper Chip

TJC Series

Features:

- High thermal conductivity
- Electrically isolated
- Aluminium nitride ceramic chips
- Compact thermal management
- Low capacitance
- Pb-free or SnPb finish
- AEC-Q200 qualified



All Pb-free parts comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

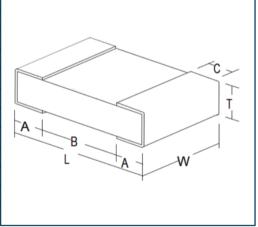


Functional Data

| | | 0603 | 0505 | 0805 | 0508 | 1206 | 0612 | 2010 | 1020 | 2512 | 1225 |
|---------------------------|------|-------------|------|------|------|------|------|------|------|------|------|
| Thermal resistance °C/W | | 13.8 | 7.4 | 11.8 | 4.6 | 14.7 | 3.7 | 15 | 3.6 | 14.9 | 3.6 |
| Thermal conductance mW/°C | | 72.5 | 135 | 84.7 | 217 | 68 | 270 | 66.7 | 278 | 67.1 | 278 |
| Capacitance typ. @1kHz pF | | 0.16 | 0.27 | 0.16 | 0.4 | 0.11 | 0.43 | 0.07 | 0.31 | 0.05 | 0.46 |
| Insulation resistance | ohms | >1G0 | | | | | | | | | |
| Ambient temperature range | °C | -55 to +155 | | | | | | | | | |

Physical Data

| Dimensions in mm and weight in mg | | | | | | | | |
|-----------------------------------|------------|------------|--------|--------|---------------|--------|----------|--|
| | L | w | T max. | A nom. | B min. | C nom. | Wt. nom. | |
| 0603 | 1.5 ±0.1 | 0.8 ± 0.1 | 0.8 | 0.59 | 0.3 | 0.59 | 3.4 | |
| 0505 | 1.21 ±0.1 | 1.21 ±0.1 | | 0.54 | 0.1 | 0.54 | 4.2 | |
| 0805 | 2 ±0.15 | 1.25 ±0.15 | | 0.69 | 0.5 | 0.69 | 5.9 | |
| 0508 | 1.25 ±0.15 | 2 ±0.15 | | 0.55 | 0.12 | 0.55 | 5.9 | |
| 1206 | 3.2 ±0.2 | 1.6 ±0.2 | | 0.71 | 1.55 | 0.71 | 11.3 | |
| 0612 | 1.6 ±0.2 | 3.2 ±0.2 | | 0.63 | 0.15 | 0.63 | 12.1 | |
| 2010 | 5.1 ±0.3 | 2.5 ±0.2 | | 0.78 | 3.4 | 0.78 | 29.2 | |
| 1020 | 2.5 ±0.2 | 5.1 ±0.3 | | 0.74 | 1 | 0.74 | 31.9 | |
| 2512 | 6.5 ±0.3 | 3.2 ±0.2 | | 0.89 | 4.3 | 0.89 | 43.9 | |
| 1225 | 3.2 ±0.2 | 6.5 ±0.3 | | 0.9 | 1.1 | 0.9 | 49.7 | |



Electronics

Construction

Ag terminations are screen printed onto an aluminium nitride (AIN) substrate. Parts are wrap-around terminated and plated with nickel then either 100% matt Sn or 60/40 SnPb.

Components are not marked. Reels are marked with type, date code and quantity.

Packing

2010, 1020, 2512 & 1225 sizes are supplied on 12mm plastic carrier tape. All smaller sizes are supplied on 8mm plastic carrier tape. All sizes are on 178mm (7 inch) reels as per IEC286-3. For packaging dimensions of sizes 0805 and larger in conventional and inverse formats

Performance Data

| Test | Method | Result | |
|---------------------|---|------------------|--|
| Temperature cycling | 1000 cycles, -55/125°C, 60 seconds transition, 30 minutes dwell | No visual damage | |
| Shear strength | 18N shear force, performed before and after temperature cycling | No visual damage | |
| Solderability | 245 ± 5°C for 2 ±0.5s | ≥95% coverage | |

www.ttelectronics.com/resistors

11.25

Thermal Jumper Chip

TJC Series



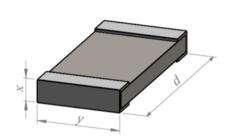
Thermal Performance Calculation

The thermal data are based on the thermal resistivity of aluminium nitride, which is 170 W/m°C. Values for Thermal Resistance (T_R) and Thermal Conductance (T_C) are obtained as follows.

$$T_R = \frac{d}{k(x,y)}$$

where k is the thermal resistivity of AlN, 170W/m°C

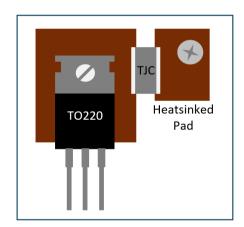
$$T_C = \frac{1}{T_R}$$



Application Notes

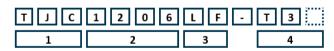
TJC is designed to provide a thermally conductive pathway with electrical isolation. It may be used as a thermal management solution for cooling PCB hotspot areas. A typical application is pictured, in which a TO220 power device is cooled by linking it to a pad which is heatsinked by a fixing which connects to the equipment chassis. Electrical isolation from the chassis must be maintained, and direct connection to a large copper groundplane is undesirable as it could lead to excessive radiated EMI.

To select the optimum size of TJC, begin by defining the range of terminal widths (W) which best matches the pad or solder joint to be cooled. Then select the shortest length dimension (L) within the constraints of capacitance and clearance requirements. The capacitance must be controlled for circuits operating at high frequency and where coupling between the pad to be cooled and the heatsink pad is undesirable. The clearance is important where high voltages can exist between the pads, and this is given by dimension B. Since the surface of the insulated body of TJC is ceramic, surface tracking is not considered an issue, so this dimension may be compared to the air clearances required in the application design.



Ordering Procedure

Example: TJC1206LF-T3 (TJC in 1206 size, Pb-free)



| 1 Series | 2 Size | 3 Finish | 4 Packing | | | | | |
|-------------|-----------|--------------|--------------|--|-----------|--------------|--|--|
| TJC | 0603 | LF = Pb-free | T4 | 0603 | 4000/reel | | | |
| | 0505 | PB = SnPb | T3 | 0505, 0805, 0508, 1206, 0612, 2010, 1020 | 3000/reel | Standard | | |
| | 0805 | | T18 | 2512, 1225 | 1800/reel | | | |
| | 0508 | | T1 | All sizes | 1000/reel | Non-standard | | |
| | 1206 | | | | | | | |
| | 0612 | | | | | | | |
| | 2010 | | | | | | | |
| | 1020 | | | | | | | |
| | 2512 | | | | | | | |
| | 1225 | | | | | | | |